

SOT1142-1

plastic thermal enhanced ball grid array package; 543 balls;
heatsink, 1 mm pitch, 27 mm x 27 mm x 1.73 mm body

19 August 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA543
Package type industry code	HBGA543
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	03-08-2009
Manufacturer package code	SOT1142

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	26.8	27	27.2	mm
package width	26.8	27	27.2	mm
seated height	2	2.23	2.45	mm
package height	1.6	1.73	1.85	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	543	-	



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2 Package outline

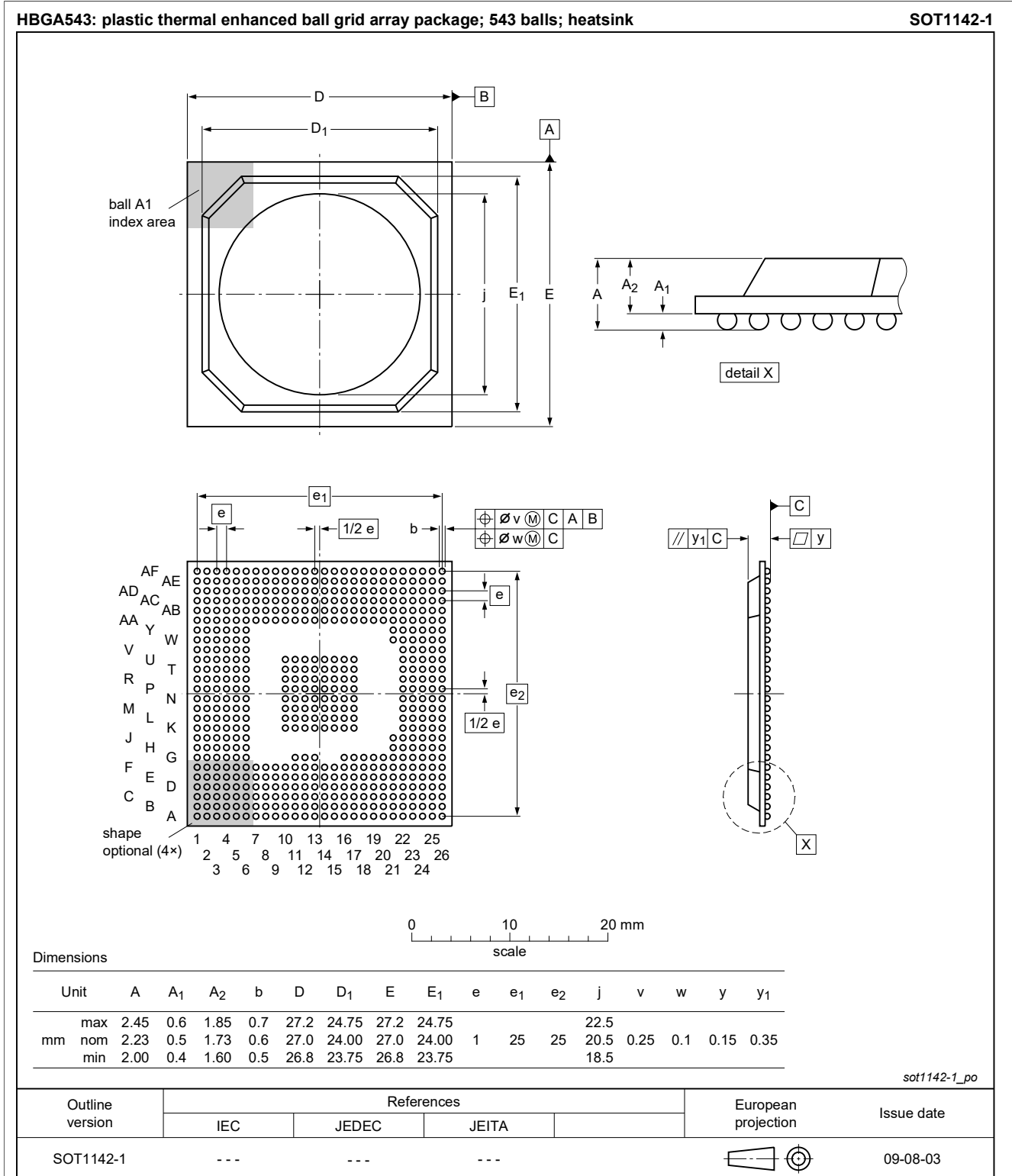


Figure 1. Package outline HBGA543 (SOT1142-1)

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3 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Legal information3